Abstracts

An Electromagnetic Technique for Packaging Problem Analysis

K.E. Krause and B.E. Spielman. "An Electromagnetic Technique for Packaging Problem Analysis." 1996 MTT-S International Microwave Symposium Digest 96.2 (1996 Vol. II [MWSYM]): 1067-1070.

A new three-dimensional electromagnetic packaging analysis is developed for shielded configurations containing arbitrarily shaped, homogeneous, isotropic regions. Computer implementation uses and extends routines from a computational engine for electromagnetic scattering. The packaging analysis is validated using rectangular waveguide configurations. Preliminary analysis is performed on a filtering structure.

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